

04-03-2008

TRADEALY IN			
Docket No.: 062758-0210 103404039			
To the Director of the C. S. I atem and Hademan Caree. I reaso record are accurate a settlements of the new address(es) below.			
1. Name of Conveying Party(ies)	2. Name and address of receiving party(ies)		
Hisashi TAKAMATSU, Takeshi YAMASHITA, Hideyuki	Name: OPNEXT JAPAN, INC.		
KUWANO, Osamu KAGAYA, Hiroyuki ARIMA			
	Internal Address:		
Additional name(s) of conveying party(ies) attached? Yes No	•		
3. Nature of Conveyance/Execution Date(s)	Address: 216, Totsuka-cho, Totsuka-ku, Yokohama-shi,		
	Kanagawa, JAPAN		
Execution Date(s): January 7, 2008, January 7, 2008, January			
7, 2008, January 7, 2008, December 28,			
2007 (respectively)			
★ Assignment			
☐ Security Agreement ☐ Change of Name			
☐ Joint Research Agreement			
Government Interest Assignment			
Executive Order 9424, Confirmatory License			
Other	Additional name(s) & address(es) attached? Yes No		
4. Application or patent number(s):	This document is being filed together with a new application.		
A. Patent Application No(s).	B. Patent No(s).		
12/003,225			
Additional numbers attached? Yes No			
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents 1 involved:		
Name: MCDERMOTT WILL & EMERY LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00		
Internal Address:	Authorized to be charged by credit card		
	Authorized to be charged to deposit account		
Street Address: 600 13th Street, N.W.	☐ Enclosed		
	None required (government interest not affecting title)		
City: Washington State: D. C. Zip: 20005-3096			
Phone Number: 202.756.8000	8. Payment Information:		
Fax Number: 202.756.8087	·		
Email Address:	a. Credit Card Last 4 Numbers		
	Expiration Date		
	b. Deposit Account Number 500417		
	Authorized User Name 94/02/2008 MJAMA1 00000048 500417 12003225		
9. Signature.	1		
Keith E. George 34,111	01 FC 16821 40.00 DA March 31, 2008		
Name and Registration No. of Person Signing Signature Date			
Total number of pages including cover sheet, attachments and documents: 2			

PATENT REEL: 020755 FRAME: 0944

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Opnext Japan, Inc., a corporation organized under the laws of Japan, located at 216, Totsuka-cho, Totsuka-ku, Yokohama-shi, Kanagawa, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Opnext Japan, Inc., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

Optical Transmitter Module

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Opnext Japan, Inc., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Opnext Japan, Inc.

Signed on the date(s) indicated aside signatures:

RECORDED: 03/31/2008

	INVENTOR(S)	Date Signed
	(発明者フルネームサイン)	(署名日)
1)	Hisashi TAKAMATSU	1/7/08
2)	Takeshi Yamashita	1/7/08
3)	$) / ! / (h \cdot) / .$	1/7/08
4)	Osamu KAGAYA	1/7/08
5)	Hiroyuki ARIMA	12/28/07
6)		
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8)		
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PATENT REEL: 020755 FRAME: 0945